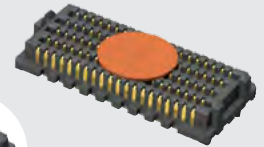


SEAM-30-03.5-S-04-2-A-K-TR



SEAM SERIES

(1.27 mm) .050"

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

- Insulator Material:** Black LCP
- Contact Material:** Copper Alloy
- Operating Temp Range:** -55 °C to +125 °C
- Current Rating (7 mm stack height):** 1.8 A per pin (10 adjacent pins powered)
- Plating:** Au or Sn over 50 μ" (1.27 μm) Ni
- Contact Resistance:** 5.5 mΩ
- Working Voltage:** 240 VAC
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

- PISMO 2
- VITA 47
- VITA 57.1

PROTOCOLS

- 100 GbE
- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™

MATED HEIGHTS			
SEAM LEAD STYLE	SEAF LEAD STYLE		
	-05.0	-06.0	-06.5
-02.0	7 mm	8 mm	8.5 mm
-03.0	8 mm	9 mm	9.5 mm
-03.5	8.5 mm	9.5 mm	10 mm
-06.5	11.5 mm	12.5 mm	13 mm
-07.0	12 mm	13 mm	13.5 mm
-09.0	14 mm	15 mm	15.5 mm
-11.0	16 mm	17 mm	17.5 mm

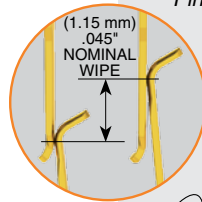
Notes: Patented

IPC-A-610F and IPC J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.

Mates with: SEAF, SEAFP

Standoffs: JSO



Up to 500 Pins

5, 8 and 10 row footprint compatible with SamArray®. Samples recommended.

Solder charges

Low insertion/extraction forces

HIGH-SPEED CHANNEL PERFORMANCE

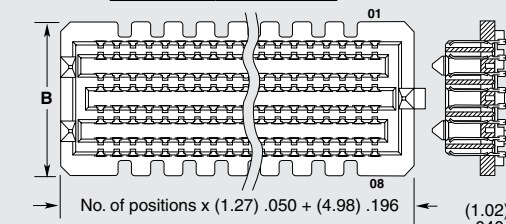
SEAM/SEAF @ 10 mm Mated Stack Height
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

34
Gbps



SEAM	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	TR
	-10, -15, -20, -30, -40, -50 (-10 only available in 04 row) (-15 is only available in 4 Row with -02.0 lead style and 10 row with any lead style)	Specify LEAD STYLE from chart	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows (-06.5 not available) -05 = Five Rows (-06.5 not available) -06 = Six Rows (-06.5 not available) -08 = Eight Rows -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge	-A = Alignment Pins (Required. Arrays will not self-center on solder pads) -K = Polyimide film Pick & Place Pad -TR = Tape & Reel		

NO. OF ROWS	B
-04	(7.06) .278
-05, -06	(9.60) .378
-08	(12.14) .478
-10	(14.68) .578



LEAD STYLE	A
-02.0	(4.60) .181
-03.0	(5.59) .220
-03.5	(6.10) .240
-06.5	(9.14) .360
-07.0	(9.60) .378
-09.0	(11.60) .457
-11.0	(13.60) .535

DIFFERENTIAL

ARRAY	PAIR COUNT	ARRAY	PAIR COUNT
40x8	80	30x8	60
40x6	60	30x6	45
30x10	75	20x10	50
50x10	125	20x8	40
50x8	100	20x5	25
40x10	100		

ALSO AVAILABLE (MOQ Required)

- Up to 560 pins
- Contact Samtec.

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